

UNISYS

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SUBJECT: Radiation Report on HST/BASE
Part No. IDT49C460
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A radiation evaluation was performed on IDT49C460 (32-Bit CMOS Error detection and Correction Unit) to determine the total dose tolerance of these parts. A brief summary of the test results is provided below. For detailed information, refer to Tables I through IV and Figure 1.

The total dose testing was performed using a ^{60}Co gamma ray source. During the radiation testing, eight parts were irradiated under bias (see Figure 1 for bias configuration), and two parts were used as control samples. The total dose radiation levels were 2.5, 5, 7.5, 10, 15, 20 and 30 krad*. The dose rate was between 0.04 and 0.6 krad/hour, depending on the total dose level (see Table II for radiation schedule). After the 30 krad irradiation, parts were annealed at 25°C for 168 hours, after which the parts were annealed at 100°C for 168 hours. After each radiation exposure and annealing treatment, parts were electrically tested according to the test conditions and the specification limits** listed in Table III. These tests included nine functional tests, six at 1.0MHz and three at 10MHz.

All parts passed initial electrical measurements. All irradiated parts passed all electrical and functional tests up to and including the 30 krad level.

After annealing for 168 hours at 25°C, all parts passed all electrical and functional tests.

After annealing for 168 hours at 100°C, no rebound effects were observed in the parts.

Table IV provides a summary of the mean and standard deviation values for each parameter after different irradiation exposures and annealing steps.

Any further details about this evaluation can be obtained upon request. If you have any questions, please call me at (301) 731-8954.

*The term rads, as used in this document, means rads(silicon). All radiation levels cited are cumulative.

**These are manufacturer's unirradiated data specification limits. No post-irradiation limits were provided by the manufacturer at the time these tests were performed.

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TABLE I. Part Information

Generic Part Number:	IDT49C460
HST/BASE Part Number:	IDT49C460DGB
HST/BASE Control Number:	10625
Charge Number:	ES44618
Manufacturer:	Integrated Device Technology
Lot Date Code:	9424
Quantity Tested:	10
Serial Number of Control Samples:	60, 63
Serial Numbers of Radiation Samples:	61, 62, 64, 65, 66, 67, 68, 69
Part Function:	32-Bit Error Detection and Correction unit
Part Technology:	CMOS
Package Style:	PGA
Test Equipment:	S-50
Test Engineer:	T. Scharer

No radiation tolerance/hardness was guaranteed by the manufacturer for this part.

TABLE II. Radiation Schedule for IDT49C460

EVENTS	DATE
1) INITIAL ELECTRICAL MEASUREMENTS	12/08/94
2) 2.5 KRAD IRRADIATION (0.04 KRADS/HOUR) POST-2.5 KRAD ELECTRICAL MEASUREMENT	12/11/94 12/12/94
3) 5 KRAD IRRADIATION (0.15 KRADS/HOUR) POST-5 KRAD ELECTRICAL MEASUREMENT	12/12/94 12/13/94
4) 7.5 KRAD IRRADIATION (0.15 KRADS/HOUR) POST-7.5 KRAD ELECTRICAL MEASUREMENT	12/14/94 12/15/94
5) 10 KRAD IRRADIATION (0.15 KRADS/HOUR) POST-10 KRAD ELECTRICAL MEASUREMENT	12/15/94 12/16/94
6) 15 KRAD IRRADIATION (0.08 KRADS/HOUR) POST-15 KRAD ELECTRICAL MEASUREMENT	12/16/94 12/19/94
7) 20 KRAD IRRADIATION (0.29 KRADS/HOUR) POST-20 KRAD ELECTRICAL MEASUREMENT	12/19/94 12/20/94
8) 30 KRAD IRRADIATION (0.59 KRADS/HOUR) POST-30 KRAD ELECTRICAL MEASUREMENT	12/20/94 12/21/94
9) 168-HOUR ANNEALING @25°C POST-168 HOUR ANNEAL ELECTRICAL MEASUREMENT	12/21/94 12/28/94
10) 168-HOUR ANNEALING @100°C* POST-168 HOUR ANNEAL ELECTRICAL MEASUREMENT (The test equipment was down until 1/10/95)	12/28/94 01/10/95

PARTS WERE IRRADIATED AND ANNEALED UNDER BIAS; SEE FIGURE 1.

*High temperature annealing is performed to accelerate long term time dependent effects (TDE), namely, the "rebound" effect due to the growth of interface states after the radiation exposure. For more information on the need to perform this test, refer to MIL-STD-883D, Method 1019, Para. 3.10.1.

Table III. Electrical Characteristics of IDT49C460

FUNCTIONAL TESTS PERFORMED

PARAMETER	VCC	VIL	VIH	CONDITIONS	PINS	LIMITS AT 3 TEMPS
FUNCT 1	4.5V	0.0V	4.5V	FREQ=1.000MHZ	ALL I/O	VOL<1.50V / VOH>1.50V
FUNCT 2	5.5V	0.0V	5.0V	FREQ=1.000MHZ	ALL I/O	VCL<1.50V / VCH>1.50V
FUNCT 3	5.5V	0.0V	5.5V	FREQ=1.000MHZ	ALL I/O	VOL<1.50V / VOH>1.50V
FUNCT 4	4.5V	0.0V	4.5V	FREQ=1.000MHZ	ALL I/O	VCL<1.50V / VCH>1.50V
FUNCT 5	5.5V	0.0V	5.0V	FREQ=1.000MHZ	ALL I/O	VOL<1.50V / VOH>1.50V
FUNCT 6	4.5V	0.0V	4.5V	FREQ=1.000MHZ	ALL I/O	VCL<1.50V / VCH>1.50V
FUNCT 7	4.5V	0.0V	4.5V	FREQ=1.000MHZ	ALL I/O	VOL<1.50V / VOH>1.50V
FUNCT 8	5.0V	0.0V	5.0V	FREQ=10.00MHZ	ALL I/O	VOL<1.50V / VOH>1.50V
FUNCT 9	5.5V	0.0V	5.5V	FREQ=10.00MHZ	ALL I/O	VOL<1.50V / VOH>1.50V

LOADS FOR ALL FUNCTIONAL TESTS ARE +/-3MA

DC PARAMETRIC TESTS PERFORMED

PARAMETER	VCC	VIL	VIH	CONDITIONS	PINS	LIMITS AT 3 TEMPS
VOH1	4.5V	0.80V	2.00V	LOAD= -300UA	OUTS	>+4.49V / <+4.50V
VOH2	4.5V	0.80V	2.00V	LOAD= -12MA	OUTS	>+2.40V / <+4.50V
VOL1	4.5V	0.80V	2.00V	LOAD= +300UA	OUTS	>-0.10V / <+0.00V
VOL2	4.5V	0.80V	2.00V	LOAD= +12MA	OUTS	>-0.00V / <+0.50V
I IH	5.5V	0.00V	5.5V	VIN = 5.5V	INS	>0UA / <+10UA
I IL	5.5V	0.00V	5.5V	VIN = 0.0V	INS	>-10UA / <0UA
I OS	5.5V	0.00V	5.5V	VOUT = 0.0V	OUTS	>-120MA / <-30MA
IOZL	5.5V	0.00V	5.5V	VOUT = 0.0V	DATA, SC	>-20UA / <0UA
IOZH	5.5V	0.00V	5.5V	VOUT = 5.5V	DATA, SC	>0UA / <+20UA
ICCC1	5.5V	0.0V	5.5V	VOUT = OPEN	VCC	>+0.0MA / <+10MA
ICCT	5.5V	0.0V	5.4V	INS=VIH	VCC	>+0.0MA / <+39MA
ICCD	5.5V	0.0V	5.5V	F=10MHZ, OE=LO	VCC	>+0.0MA / <+100MA
ICC1	5.5V	0.0V	5.5V	F=10MHZ, OE=LO	VCC	>+0.0MA / <+110MA
ICC2	5.5V	0.4V	5.4V	F=10MHZ, OE=LO	VCC	>+0.0MA / <+125MA

AC PARAMETRIC TESTS PERFORMED

PARAMETER	VCC	VIL	VIH	CONDITIONS	PINS	LIMITS AT +25C ONLY
TPLHC -SC	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+13NS
TPLHC -E	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+12NS
TPLHC -M	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+14NS
TPLAD -SC	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+17NS
TPHLC -SC	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+13NS
TPHLC -E	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+12NS
TPHLC -M	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+14NS
TPHLD -SC	4.5V	0.00V	3.00V	VTEST= 1.5V	OUTS	>+1.0NS / <+17NS

COMMENTS/EXCEPTIONS

- (1) THE MAXIMUM LIMIT FOR ICCT IS (53 INPUTS)*(0.75MA/INPUT) OR 39.75MA. A ROUNDED LIMIT OF 39MA IS USED WHICH IS LESS THAN THE ACTUAL MAXIMUM.
- (2) VIH AND VIL ARE TESTED GO/NOGO DURING THE VOH AND VOL TESTS. VIL FOR THE ENABLE PINS ARE TESTED GO/NOGO DURING THE IOZ TESTS.
- (3) ONLY THE AC'S LISTED ARE TESTED. ALL OTHER AC PARAMETERS LISTED IN THE DATA SHEET ARE NOT TESTED. THIS INCLUDES SETUP AND HOLD TIMES.
- (4) THE VOH1 LOWER LIMIT IS 4.49V AND NOT THE 4.5V (VCC) LISTED IN THE DATA SHEET. THE ACCURACY OF THE PMU ON THE 8V RANGE IS 12.098MV. ALL RESULTS USING THE 8V RANGE ARE TRUNCATED TO TWO DECIMAL PLACES. THEREFORE ALL READINGS OF 4.49X V ARE LISTED AS 4.49V. THE PMU ACCURACY PREVENTS A LOWER LIMIT OF 4.5V FROM BEING USED.
- (5) THE VOL1 RESULTS FORCE ANY READING OF 1MV OR LESS TO 0V.
- (6) THE MAXIMUM LIMIT FOR ICCD IS (10MHZ)*(10MA/MHZ) OR 100MA.

Figure 1. Radiation Bias Circuit for IDT49C460

PIN LOC	BURN IN CONNECT	SIGNAL NAME	SIGNAL NAME	BURN IN CONNECT	PIN LOC
=====	=====	=====	=====	=====	=====
B2	+5.0V	VCC	D[1]	+5.0V	A2
B1	0.0V	D[2]	D[0]	0.0V	A3
C2	+5.0V	D[3]	OE [0]	+5.0V	A4
C1	0.0V	D[4]	LEIN	+5.0V	A5
D2	+5.0V	D[5]	DIAG MODE [1]	0.0V	A6
D1	0.0V	D[6]	DIAG MODE [0]	0.0V	A5
E2	+5.0V	D[7]	CODE ID [1]	+5.0V	A6
E1	0.0V	D[8]	CODE ID [0]	0.0V	A6
F2	GROUND	GND	OE [3]	+5.0V	B6
F1	+5.0V	D[9]	D[31]	+5.0V	A7
G2	0.0V	D[10]	D[30]	0.0V	B7
G1	+5.0V	D[11]	D[29]	+5.0V	B8
H2	0.0V	D[12]	D[28]	0.0V	B8
H1	+5.0V	D[13]	D[27]	+5.0V	A9
J2	0.0V	D[14]	D[26]	0.0V	B9
J1	+5.0V	D[15]	D[25]	+5.0V	A10
K1	+5.0V	OE [1]	GND	GROUND	B10
K2	0.0V	CB[7]	D[24]	0.0V	B11
L2	0.0V	CB[6]	D[23]	+5.0V	C11
L1	0.0V	CB[5]	D[22]	0.0V	C10
M2	0.0V	CB[4]	D[21]	+5.0V	D11
M1	+5.0V	CB[3]	D[20]	+5.0V	D10
N2	+5.0V	CB[2]	D[19]	+5.0V	E11
N1	0.0V	CB[1]	D[18]	0.0V	E10
X2	VCC/2	SC[0]	D[17]	+5.0V	F11
X1	VCC/2	SC[1]	VCC	+5.0V	F10
Y2	VCC/2	SC[2]	D[16]	0.0V	G11
Y1	VCC/2	SC[3]	OE [2]	+5.0V	G10
Z2	VCC/2	SC[4]	LEOUT/GEN_	+5.0V	H11
Z1	VCC/2	SC[5]	CORRECT	0.0V	H10
AA2	VCC/2	SC[6]	LEDIAG	+5.0V	J11
AA1	VCC/2	SC[7]	ERROR	VCC/2	J10
AB2	VCC/2	OE SC_	MULTI ERROR_	VCC/2	K11
AB1	0.0V		GND	GROUND	K10

VCC = +5 V +/- 0.5 V
 VCC/2 = +2.5 V +/- 0.25 V
 TA = +25 AND +100C